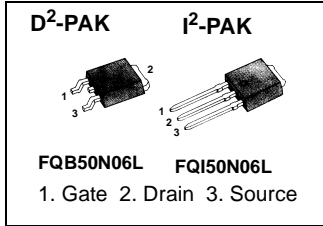


FEATURES

- Advanced New Design
- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Very Low Intrinsic Capacitances
- Excellent Switching Characteristics
- Unrivalled Gate Charge: 24.5nC (Typ.)
- Extended Safe Operating Area
- Lower $R_{DS(ON)}$: 0.017Ω (Typ.)

$V_{DSS} = 60V$
 $R_{DS(ON)} = 0.021\Omega$
 $I_D = 52.4A$



ABSOLUTE MAXIMUM RATINGS

Symbol	Characteristics	Value	Units
V_{DSS}	Drain-to-Source Voltage	60	V
I_D	Continuous Drain Current ($T_C = 25^\circ C$)	52.4	A
	Continuous Drain Current ($T_C = 100^\circ C$)	37.1	
I_{DM}	Drain Current-Pulsed ①	210	A
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulsed Avalanche Energy ②	990	mJ
I_{AR}	Avalanche Current ①	52.4	A
E_{AR}	Repetitive Avalanche Energy ①	12.1	mJ
dv/dt	Peak Diode Recovery dv/dt ③	7.0	V/ns
P_D	Total Power Dissipation ($T_A = 25^\circ C$) *	3.8	W
	Total Power Dissipation ($T_C = 25^\circ C$) Linear Derating Factor	121 0.81	W W/°C
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 to +175	°C
T_L	Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5-seconds	300	

THERMAL RESISTANCE

Symbol	Characteristics	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	-	1.24	°C/W
$R_{\theta JA}$	Junction-to-Ambient *	-	40	
$R_{\theta JA}$	Junction-to-Ambient	-	62.5	

* When mounted on the minimum pad size recommended (PCB Mount)

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristics	Min.	Typ.	Max.	Units	Test Conditions
BV_{DSS}	Drain-Source Breakdown Voltage	60	–	–	V	$V_{GS}=0V, I_D=250\mu A$
$\Delta BV/\Delta T_J$	Breakdown Voltage Temp. Coeff.	–	0.06	–	V/ $^\circ\text{C}$	$I_D=250\mu A$, See Fig 7
$V_{GS(th)}$	Gate Threshold Voltage	1.0	–	2.5	V	$V_{DS}=5V, I_D=250\mu A$
I_{GSS}	Gate-Source Leakage, Forward	–	–	100	nA	$V_{GS}=20V$
	Gate-Source Leakage, Reverse	–	–	–100		$V_{GS}= -20V$
I_{DSS}	Drain-to-Source Leakage Current	–	–	1	μA	$V_{DS}=60V$
		–	–	10		$V_{DS}=48V, T_C=150^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-State Resistance	–	–	0.021	Ω	$V_{GS}=10V, I_D=26.2A$ ④
		–	–	0.025		$V_{GS}=5V, I_D=26.2A$ ④
g_{fs}	Forward Transconductance	–	40	–	S	$V_{DS}=25V, I_D=26.2A$ ④
C_{iss}	Input Capacitance	–	1250	1630	pF	$V_{GS}=0V, V_{DS}=25V$ $f=1\text{MHz}$ See Fig 5
C_{oss}	Output Capacitance	–	445	580		
C_{rss}	Reverse Transfer Capacitance	–	90	120		
$t_{d(on)}$	Turn-On Delay Time	–	20	50	ns	$V_{DD}=30V, I_D=26.2A$ $R_G=50\Omega$ See Fig 13 ④ ⑤
t_r	Rise Time	–	380	770		
$t_{d(off)}$	Turn-Off Delay Time	–	80	170		
t_f	Fall Time	–	145	300		
Q_g	Total Gate Charge	–	24.5	32	nC	$V_{DS}=48V, V_{GS}=5V$ $I_D=52.4A$ See Fig 6 & Fig 12 ④ ⑤
Q_{gs}	Gate-Source Charge	–	6	–		
Q_{gd}	Gate-Drain (Miller) Charge	–	14.5	–		

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristics	Min.	Typ.	Max.	Units	Test Conditions
I_S	Continuous Source Current	–	–	52.4	A	Integral reverse pn-diode in the MOSFET
I_{SM}	Pulsed-Source Current ①	–	–	210		
V_{SD}	Diode Forward Voltage ④	–	–	1.5	V	$T_J=25^\circ\text{C}, I_S=52.4A, V_{GS}=0V$
t_{rr}	Reverse Recovery Time	–	65	–	ns	$T_J=25^\circ\text{C}, I_F=52.4A, V_{DD}=48V$ $di_F/dt=100A/\mu s$ ④
Q_{rr}	Reverse Recovery Charge	–	125	–	nC	

Notes:

- ① Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
- ② $L=300\mu H, I_{AS}=52.4A, V_{DD}=25V, R_G=25\Omega$, Starting $T_J = 25^\circ\text{C}$
- ③ $I_{SD} \leq 52.4A, di/dt \leq 300A/\mu s, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
- ④ Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$
- ⑤ Essentially Independent of Operating Temperature

Fig 1. Output Characteristics

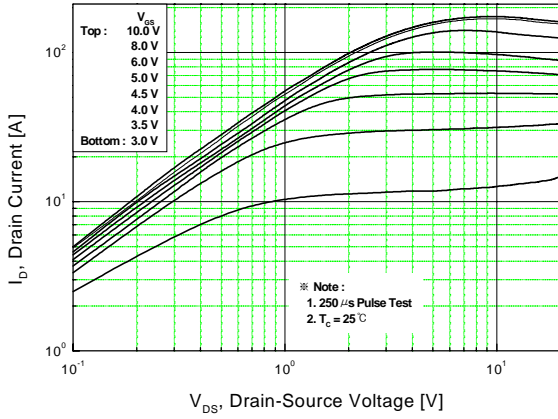


Fig 2. Transfer Characteristics

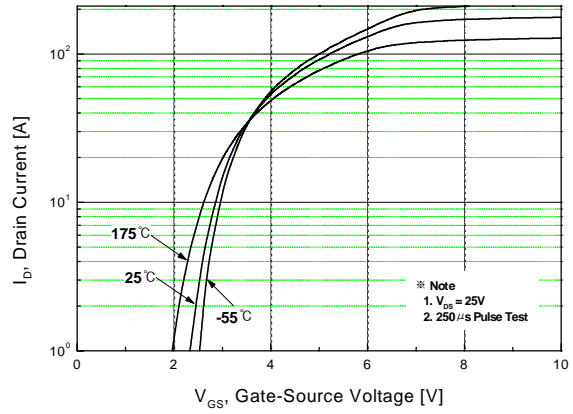


Fig 3. On-Resistance vs. Drain Current

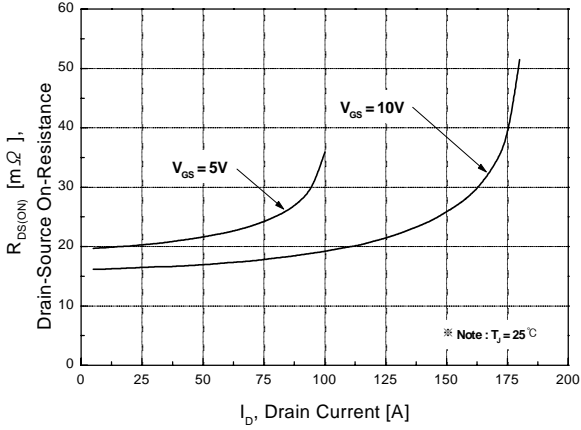


Fig 4. Source-Drain Diode Forward Voltage

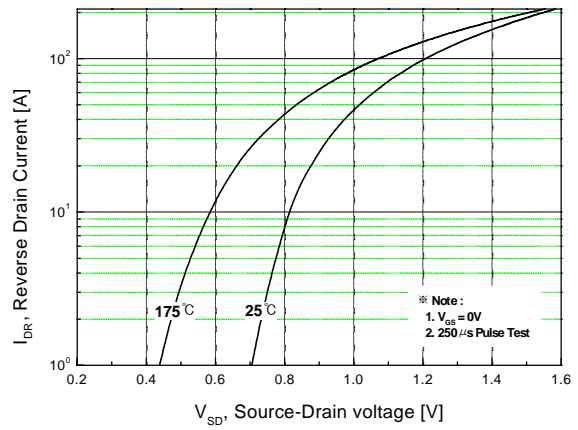


Fig 5. Capacitance vs. Drain-Source Voltage

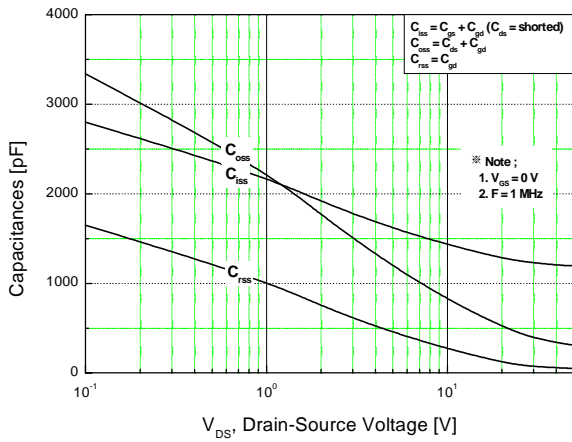


Fig 6. Gate Charge vs. Gate-Source Voltage

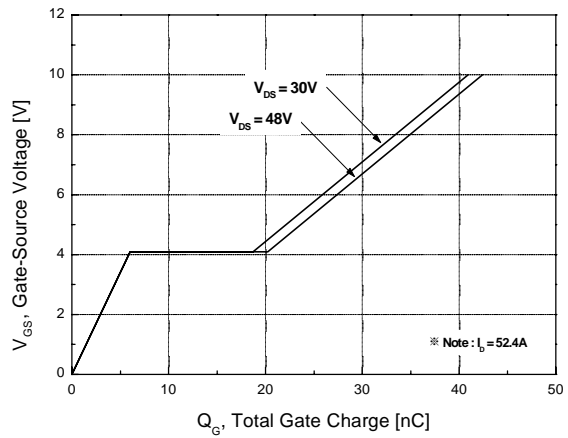


Fig 7. Breakdown Voltage vs. Temperature

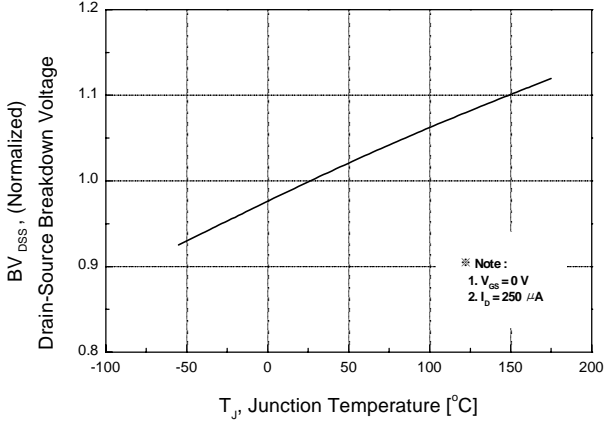


Fig 8. On-Resistance vs. Temperature

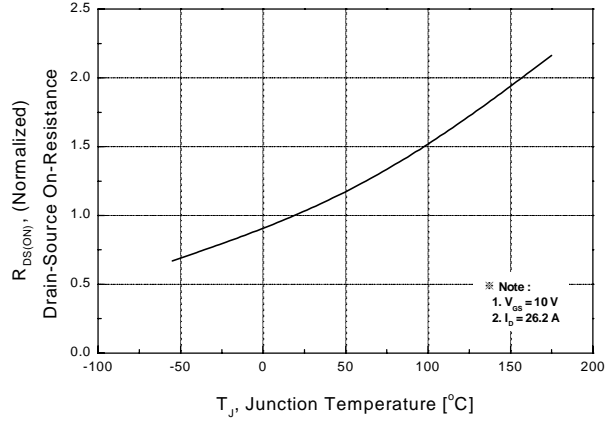


Fig 9. Max. Safe Operating Area

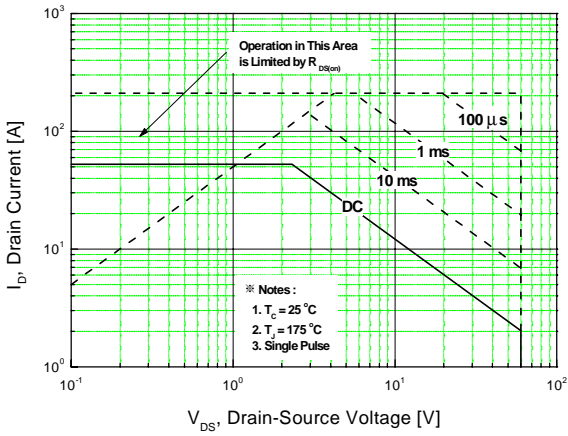


Fig 10. Max. Drain Current vs. Case Temperature

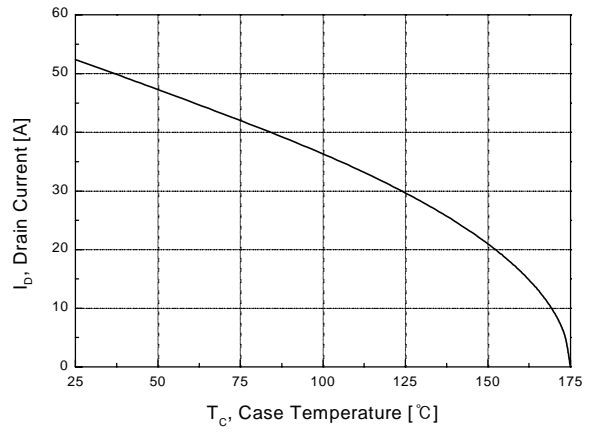


Fig 11. Thermal Response

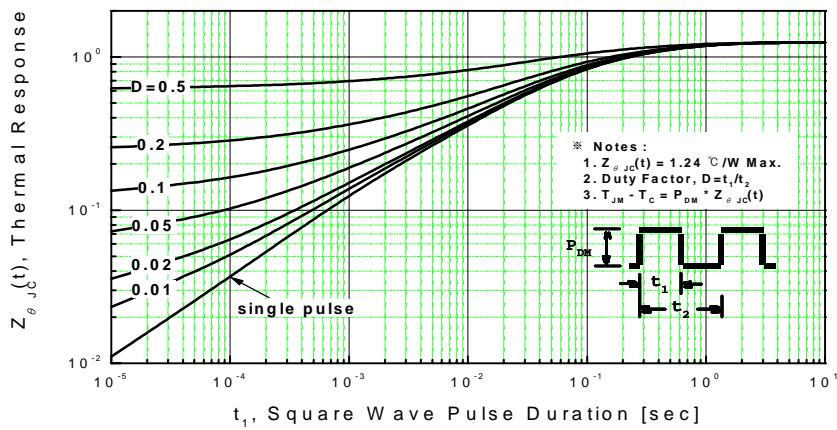


Fig 12. Gate Charge Test Circuit & Waveform

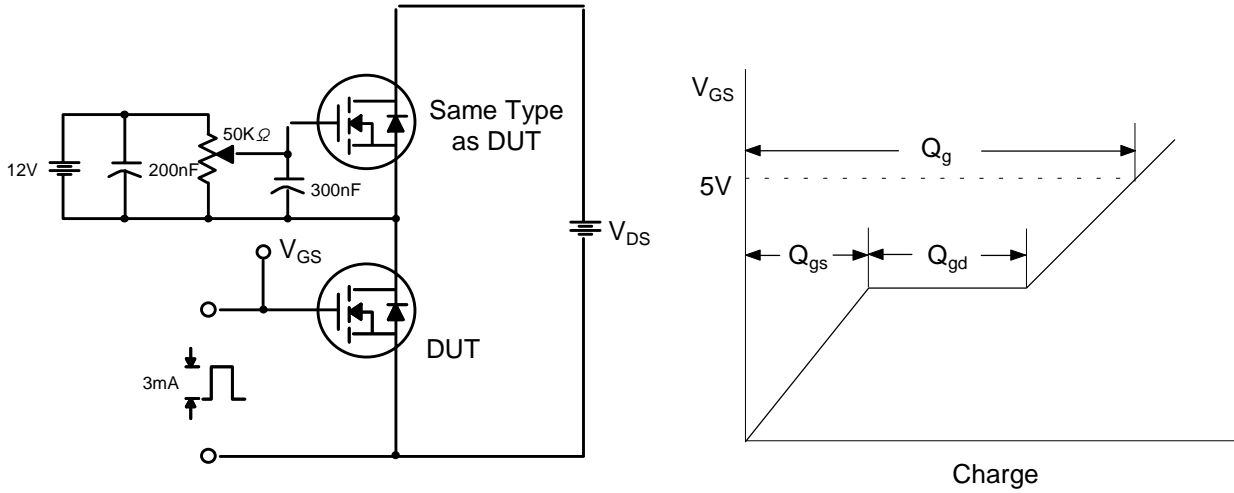


Fig 13. Resistive Switching Test Circuit & Waveforms

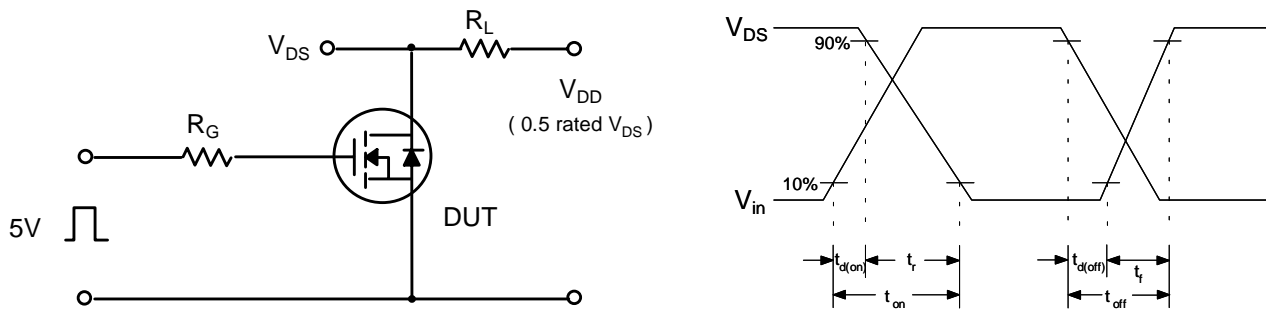


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

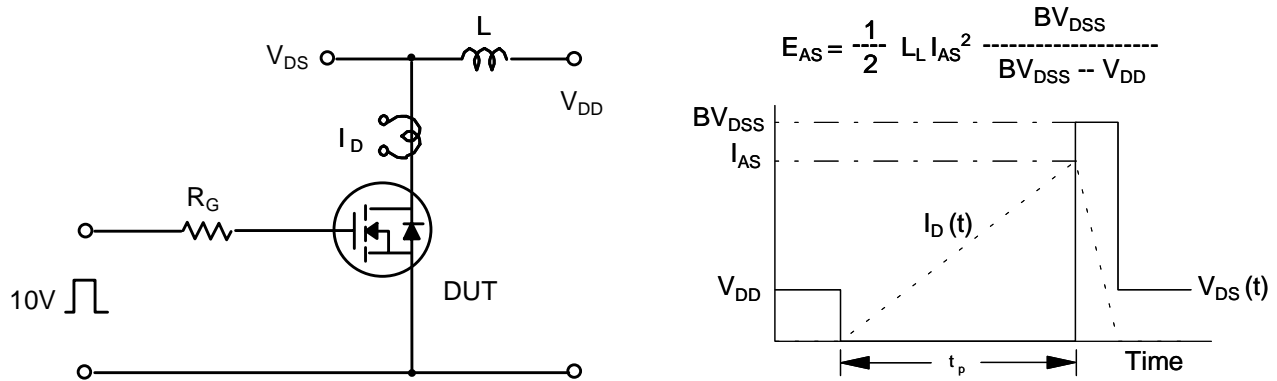
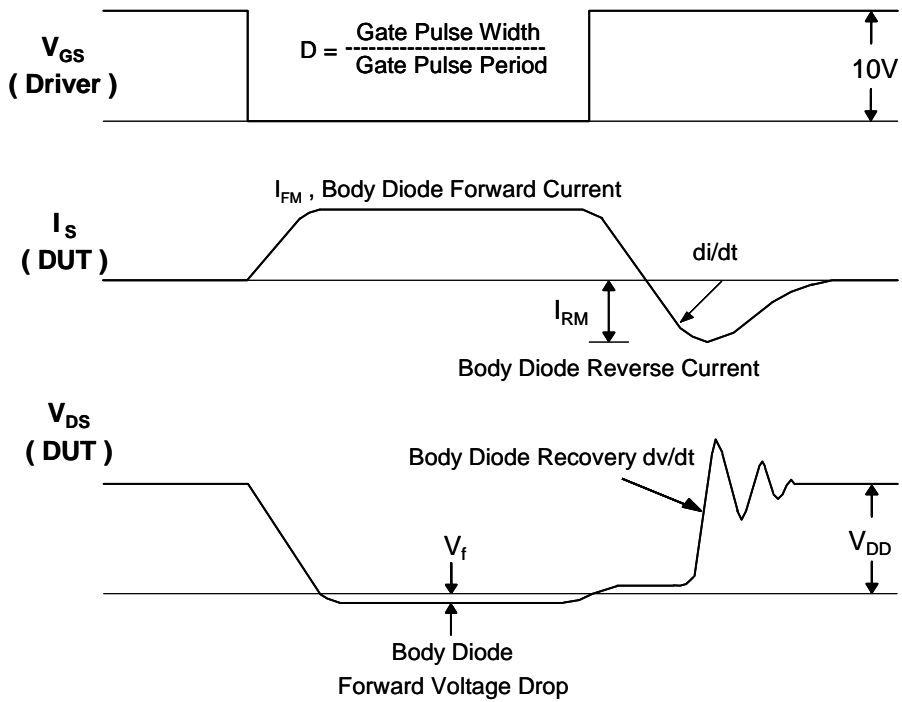
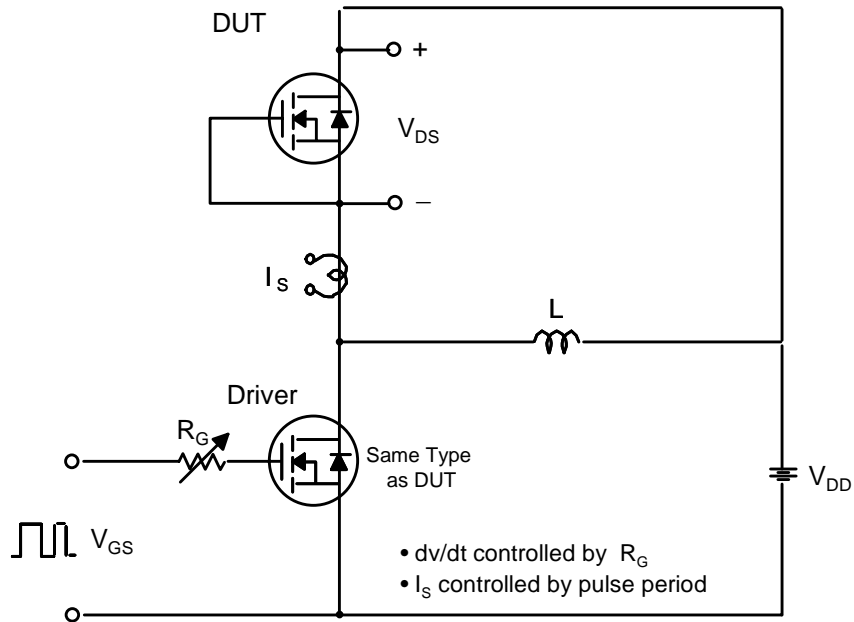


Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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